

FS30AS-2

High-Speed Switching Use Nch Power MOS FET

REJ03G1411-0200

(Previous: MEJ02G0100-0101)

Rev.2.00 Aug 07, 2006

Features

• Drive voltage: 10 V

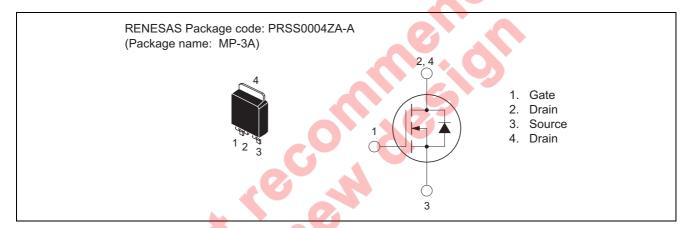
• V_{DSS}: 100 V

• $r_{DS(ON) \, (max)}$: 100 m Ω

• I_D: 30 A

• Integrated Fast Recovery Diode (TYP.): 95 ns

Outline



Applications

Motor control, Lamp control, Solenoid control, DC-DC converters, etc.

Maximum Ratings

 $(Tc = 25^{\circ}C)$

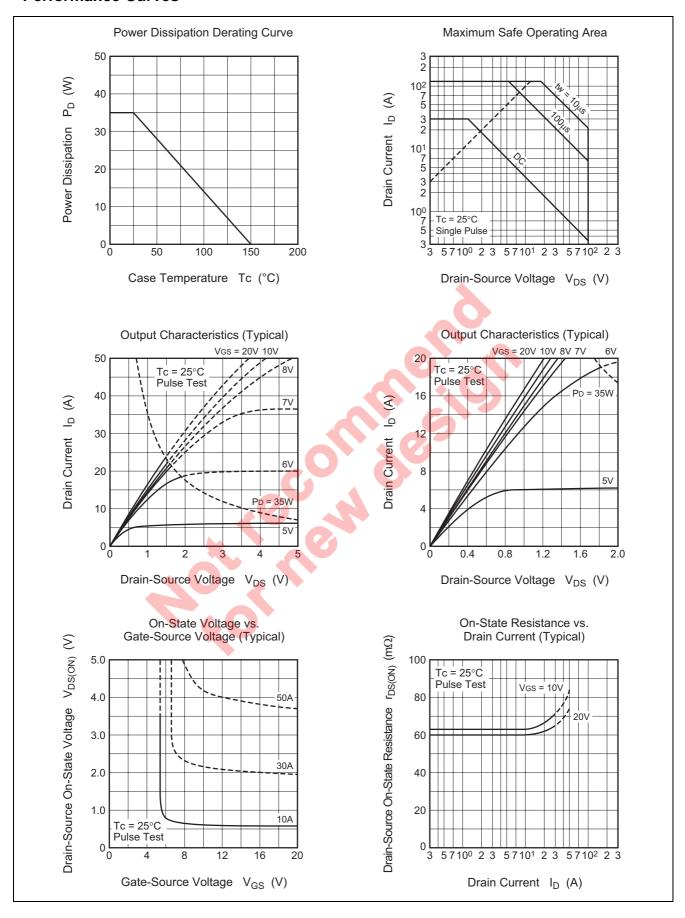
Parameter	Symbol	Ratings	Unit	Conditions
Drain-source voltage	V _{DSS}	100	V	V _{GS} = 0 V
Gate-source voltage	V _{GSS}	±20	V	$V_{DS} = 0 V$
Drain current	I _D	30	А	
Drain current (Pulsed)	I _{DM}	120	А	
Avalanche drain current (Pulsed)	I _{DA}	30	А	L = 100 μH
Source current	Is	30	А	
Source current (Pulsed)	I _{SM}	120	А	
Maximum power dissipation	P _D	35	W	
Channel temperature	Tch	- 55 to +150	°C	
Storage temperature	Tstg	- 55 to +150	°C	
Mass	_	0.32	g	Typical value

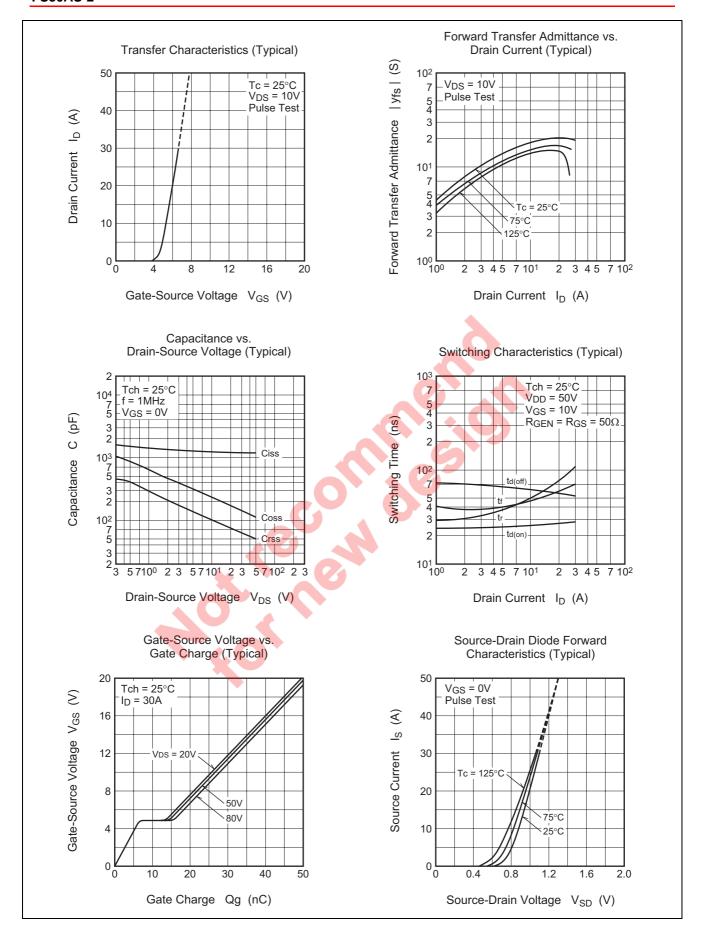
Electrical Characteristics

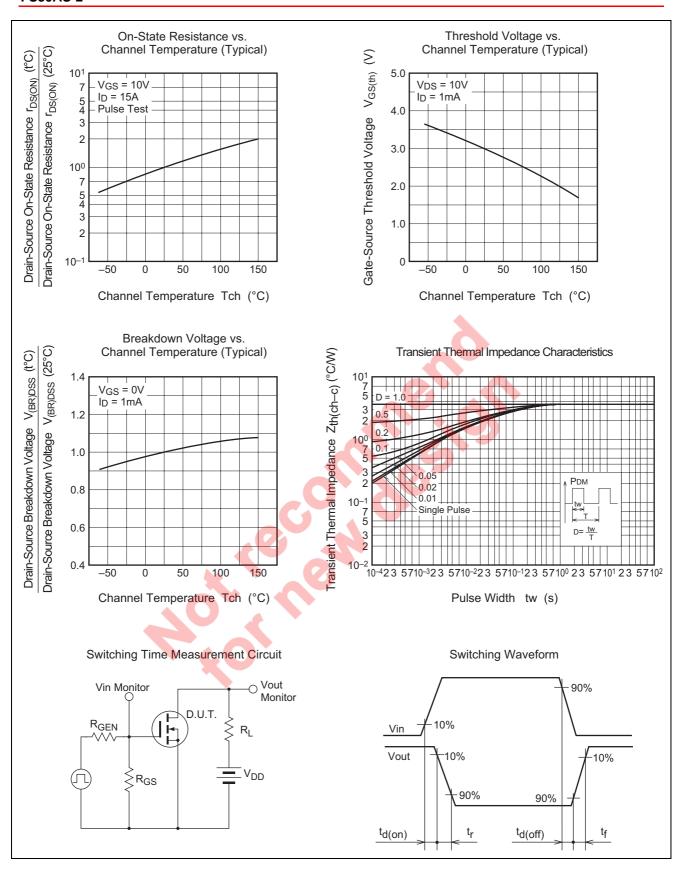
 $(Tch = 25^{\circ}C)$

Parameter	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain-source breakdown voltage	V _{(BR)DSS}	100		_	V	$I_D = 1 \text{ mA}, V_{GS} = 0 \text{ V}$
Gate-source leakage current	I _{GSS}	_	_	±0.1	μΑ	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$
Drain-source leakage current	I _{DSS}	_	_	0.1	mA	V _{DS} = 100 V, V _{GS} = 0 V
Gate-source threshold voltage	V _{GS(th)}	2.0	3.0	4.0	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Drain-source on-state resistance	r _{DS(ON)}	_	69	100	mΩ	I _D = 15 A, V _{GS} = 10 V
Drain-source on-state voltage	V _{DS(ON)}	_	1.04	1.50	V	I _D = 15 A, V _{GS} = 10 V
Forward transfer admittance	y _{fs}	_	18		S	I _D = 15 A, V _{DS} = 10 V
Input capacitance	Ciss		1250		pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V},$
Output capacitance	Coss		230		pF	f = 1MHz
Reverse transfer capacitance	Crss		105	_	pF	
Turn-on delay time	t _{d(on)}	_	25	_	ns	$V_{DD} = 50 \text{ V}, I_D = 15 \text{ A},$
Rise time	t _r	_	60	_	ns	V _{GS} = 10 V,
Turn-off delay time	t _{d(off)}	_	60	_	ns	$R_{GEN} = R_{GS} = 50 \Omega$
Fall time	t _f	_	50	_	ns	
Source-drain voltage	V _{SD}	_	1.0	1.5	V	I _S = 15 A, V _{GS} = 0 V
Thermal resistance	R _{th(ch-c)}	_		3.57	°C/W	Channel to case
Reverse recovery time	t _{rr}	_	95		ns	$I_S = 30 \text{ A}, d_{is}/d_t = -100 \text{ A/}\mu\text{s}$
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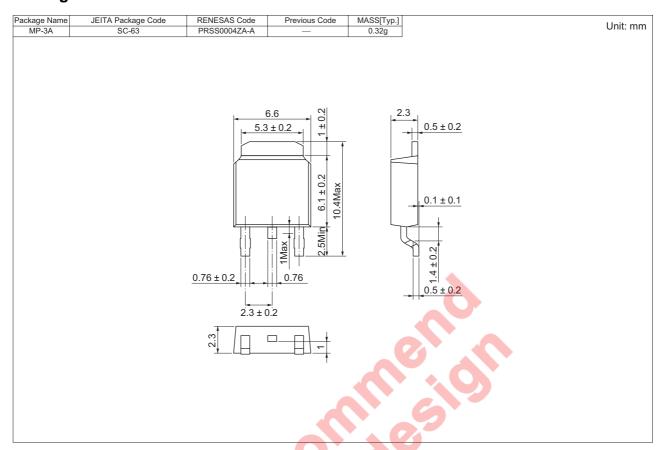
Performance Curves







Package Dimensions



Order Code

Lead form	Standard packing	Quantity	Standard order code	Standard order code example
Surface-mounted type	Taping	3000	Type name – T +Direction (1 or 2) +3	FS30AS-2-T13
Surface-mounted type	Plastic Magazine (Tube)	75	Type name	FS30AS-2

Note: Please confirm the specification about the shipping in detail.

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